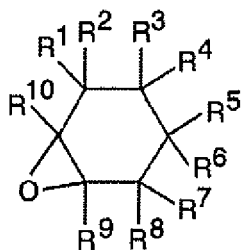


AMENDED CLAIM SET:

1. (withdrawn) A heat-curable resin composition comprising an alicyclic epoxy compound (a) having a structure represented by the following general formula (1),

General formula (1)

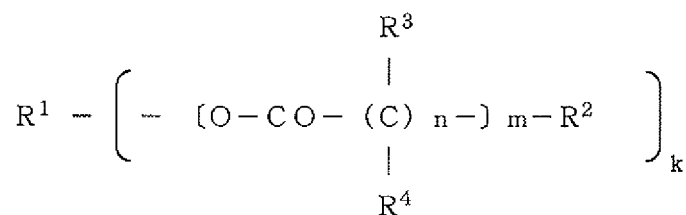


wherein, in the general formula (1): R^1 to R^{10} each represent hydrogen, or a saturated or unsaturated hydrocarbon group having 1 to 20 carbon atoms, wherein an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group; R^1 to R^{10} may each represent a residue derived by removing any one of R^1 to R^{10} from the structure represented by the general formula (1), or a residue derived by removing hydrogen from any one of R^1 to R^{10} ; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group", a cationic polymerization initiator (i), and a surfactant (e), wherein the surfactant (e) comprises a silicon-based surfactant (e1) having a dimethylsiloxane skeleton and/or a fluorine-based surfactant (e2) having hydrophobic groups of a hydrocarbon-based surfactant entirely or partially substituted with fluorine atoms.

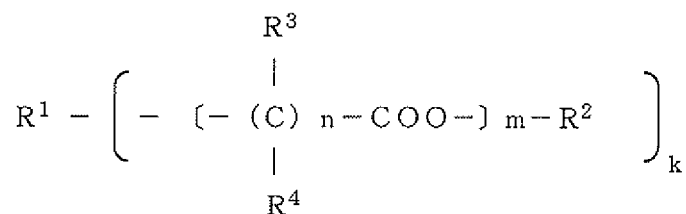
2. (withdrawn) A heat-curable resin composition according to claim 1, further comprising a polyol (b) having two or more hydroxyl groups on terminals.

3. (previously presented) A heat-curable resin composition comprising an alicyclic epoxy compound (a') having a structure represented by the following general formula (2),

General formula (2)

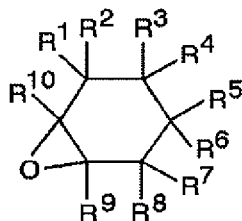


or



wherein, in the general formula (2): R^1 represents hydrogen, or a hydrocarbon group of a valence k having 1 to 20 carbon atoms, wherein an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group; R^2 represents hydrogen, a hydroxyl group, or a hydrocarbon group having 1 to 20 carbon atoms, wherein an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group; at least one of R^1 and R^2 represents a residue derived by removing any one of R^1 to R^{10} from the structure represented by the following general formula (1); R^3 and R^4 each represents hydrogen, or a hydrocarbon group having 1 to 20 carbon atoms; a plurality of R^3 's and R^4 's may be the same or different from each other; "n" represents an integer of 3 to 10; "m" represents an integer of 2 to 10; "k" represents an integer of 1 to 10; when "k" is 2 or more, the variables R^2 , R^3 , R^4 , n, and m may be the same or different from each other; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group", and the following general formula (1),

General formula (1)



wherein, in the general formula (1): R^1 to R^{10} each represent hydrogen, or a saturated or unsaturated hydrocarbon group having 1 to 20 carbon atoms, wherein an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group; R^1 to R^{10} may each represent a residue derived by removing any one of R^1 to R^{10} from the structure represented by the general formula (1), or a residue derived by removing hydrogen from any one of R^1 to R^{10} ; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group", a cationic polymerization initiator (i), and a surfactant (e), wherein the surfactant (e) comprises a silicon-based surfactant (e1) having a dimethylsiloxane skeleton and/or a fluorine-based surfactant (e2) having hydrophobic groups of a hydrocarbon-based surfactant entirely or partially substituted with fluorine atoms.

4. – 6. (cancelled).

7. – 10. (cancelled).

11. (withdrawn) A heat-curable resin composition according to claim 2, wherein the content of the surfactant (e) is 0.05 to 5 parts by weight with respect to 100 parts by weight of the alicyclic epoxy compound (a) and the polyol (b) in total.

12. (previously presented) A heat-curable resin composition according to claim 3, wherein the content of the surfactant (e) is 0.05 to 5 parts by weight with respect to 100 parts by weight of the alicyclic epoxy compound (a') in total.

13. (withdrawn) A heat-curable resin composition according to any one of claims 1, 2, and 11, wherein the surfactant (e) is a silicon-based surfactant (e1) having a dimethylsiloxane skeleton.

14. (previously presented) A heat-curable resin composition according to claim 3 or 12, wherein the surfactant (e) is a silicon-based surfactant (e1) having a dimethylsiloxane skeleton.

15. (previously presented) A heat-curable resin composition according to claim 3 or 12, wherein the surfactant (e) is a fluorine-based surfactant (e2) having hydrophobic groups of a hydrocarbon-based surfactant entirely or partially substituted with fluorine atoms.

16. (new) A cured product, which is obtained by heat curing the heat-curable resin composition according to any one of claims 1 to 3 and 11 to 15.

17. (new) The cured product according to claim 16, which is used for an adhesive or an encapsulant.

18. (new) The cured product according to claim 16, wherein a warping by shrinkage in curing is 15 mm or less through a measurement method A, 6 mm or less through a measurement method B.

19. (new) The cured product according to claim 17, wherein a warping by shrinkage in curing is 15 mm or less through a measurement method A, 6 mm or less through a measurement method B.

20. (new) The heat-curable resin composition according to claim 3, wherein the alicyclic epoxy compound (a') consists essentially of ϵ -caprolactone denaturation 3,4-epoxycyclohexylmethyl-3',4'-epoxycyclohexylcarboxylate (CEL2081).

21. (new) A process for the production of a cured product, the process comprising the step of heating the heat-curable resin composition according to claim 3.